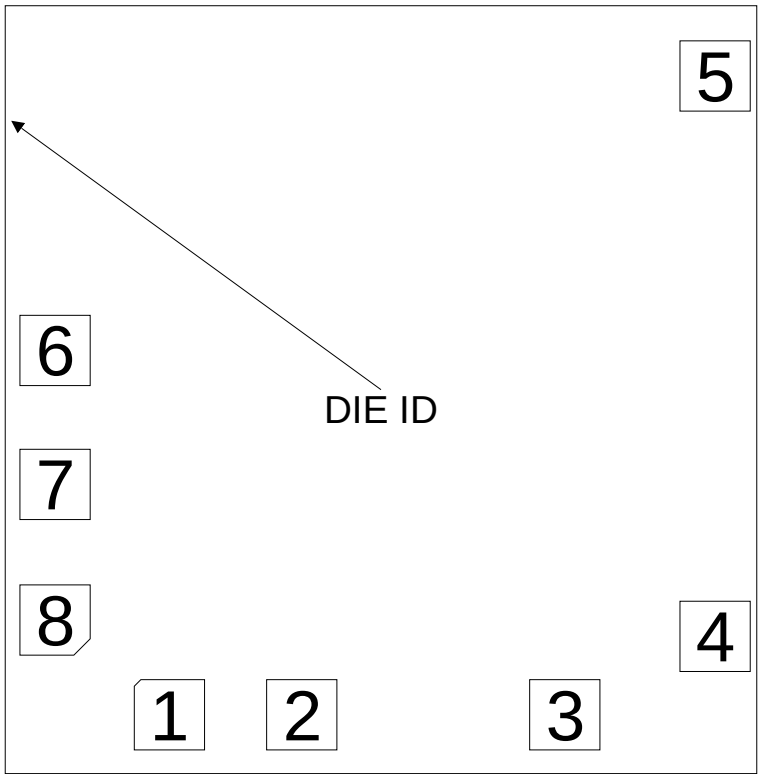
LM101A MD8 MCD2830A
OPERATIONAL AMPLIFIER

MAY 09, 2008

DIE LAYOUT (F-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM101	Bond Pad Opening Size (min)	109.22µm x 109.22µm
Die Step	F	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	PECVDOX NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1168.4µm x 1193.8µm 46.0mils x 47.0mils	Back Side Connection	Floating
Thickness	330µm Nominal		
Min Pitch	205µm		
Note: All values are rounded to the nearest micron.			
Special Assembly Requirements:			

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Die Bond Pad Coordinate Locations(F-Step)
(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X		Y
BALANCE COMP	1	-328	-505	109	x	109
INPUT -	2	-123	-505	109	x	109
INPUT +	3	285	-505	109	x	109
V -	4	519	-383	109	x	109
BALANCE	5	519	487	109	x	109
OUTPUT	6	-506	60	109	x	109
V +	7	-506	-147	109	x	109
COMPENSATION	8	-506	-358	109	x	109

Notes

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